HOLE CHART

<table>
<thead>
<tr>
<th>FIGURE</th>
<th>SIZE</th>
<th>TOLERANCE</th>
<th>PLATED</th>
<th>QTY</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>30.0</td>
<td>+0.0/0.0</td>
<td>PLATED</td>
<td>1305</td>
</tr>
<tr>
<td></td>
<td>38.0</td>
<td>+0.0/0.0</td>
<td>PLATED</td>
<td>58</td>
</tr>
<tr>
<td>+</td>
<td>24.0</td>
<td>+0.0/0.0</td>
<td>PLATED</td>
<td>2</td>
</tr>
<tr>
<td>+</td>
<td>26.0</td>
<td>+0.0/0.0</td>
<td>PLATED</td>
<td>10</td>
</tr>
<tr>
<td>+</td>
<td>30.0</td>
<td>+0.0/0.0</td>
<td>PLATED</td>
<td>6</td>
</tr>
<tr>
<td>+</td>
<td>37.0</td>
<td>+0.0/0.0</td>
<td>PLATED</td>
<td>42</td>
</tr>
<tr>
<td>+</td>
<td>43.0</td>
<td>+0.0/0.0</td>
<td>PLATED</td>
<td>24</td>
</tr>
<tr>
<td>O</td>
<td>79.0</td>
<td>+0.0/0.0</td>
<td>PLATED</td>
<td>2</td>
</tr>
<tr>
<td>O</td>
<td>126.0</td>
<td>+0.0/0.0</td>
<td>PLATED</td>
<td>6</td>
</tr>
<tr>
<td>+</td>
<td>49.0</td>
<td>+0.0/0.0</td>
<td>NON-PLATE</td>
<td>2</td>
</tr>
<tr>
<td>B</td>
<td>138.0x31.0</td>
<td>+3.0/-3.0</td>
<td>PLATE</td>
<td>2</td>
</tr>
<tr>
<td></td>
<td>138.0x31.0</td>
<td>+3.0/-3.0</td>
<td>PLATE</td>
<td>1</td>
</tr>
</tbody>
</table>

FAB NOTES

1. MATERIAL: 0.008"+-30% THICK FR-4 OR EQUIVALENT. BOARD CONSTRUCTION SEE SECTION A-A.
2. SURFACE FINISHES: AN ELECTROPLATE NICKEL AND DIMENSION GOLD PROCESS.
3. GOLD SHALL BE 3 MICRO INCHES OVER 150 MICRO INCHES NICKEL.
4. TRACE WIDTH TOLERANCE SHALL BE +/- 10% OF DATED SIZES.
5. MOUNT HOLE SIZES. SEE HOLE CHART, UNLESS OTHERWISE SPECIFIED, ALL HOLE
   DIMENSIONS ARE AFTER PLATING. ALL PLATED THROUGH HOLES TO HAVE A
   MINIMUM OF 0.001" OF COPPER. ALL HOLES SHALL BE LOCATED WITHIN 0.007" 
   DIAMETER OF GEOMETRIC TRUE POSITION.
6. LAYER TO LAYER REGISTRATION SHALL BE +/- 0.005".
7. ALL HOLES SURROUNDED BY LAMINATE SHALL HAVE A MINIMUM ANULAR RING OF 0.002".
8. FILM TYPE:
   a) POSITIVE ON LAYERS 1, 3, 4-6, 9, 10 AND 12.
   b) NEGATIVE ON LAYERS 2, 5-8 AND 11.
9. SOLDERWASH COLOR: BLUE.
10. SOLDERABLE IMPEDANCE SHALL BE 50 OHMS +/- 10% FOR ALL 5 MIL TRACES ON LAYERS 1, 3, 4-6, 9, 10 AND 12.
    a) DIFFERENTIAL IMPEDANCE SHALL BE 100 OHMS +/- 10% FOR ALL 7 MIL TRACES ON LAYERS 1 AND 12.
    b) DIFFERENTIAL TRACES GAP 16 MIL.
    c) DIFFERENTIAL TRACES GAP 8 MIL.

CROSS SECTION

LAYER 1: PRIMARY SIDE
1/2 OZ PLATER TO 1.0 OZ
LAYER 2: GROUND PLANE
3 OZ COPPER
LAYER 3: INTERMEDIATE TRACES
2 OZ COPPER
LAYER 4: POWER PLANE
3 OZ COPPER
LAYER 5: INTERMEDIATE TRACES
2 OZ COPPER
LAYER 6: INTERMEDIATE TRACES
2 OZ COPPER
LAYER 7: POWER PLANE
3 OZ COPPER
LAYER 8: INTERMEDIATE TRACES
2 OZ COPPER
LAYER 9: INTERMEDIATE TRACES
2 OZ COPPER
LAYER 10: INTERMEDIATE TRACES
2 OZ COPPER
LAYER 11: INTERMEDIATE TRACES
1.5 OZ COPPER
LAYER 12: INTERMEDIATE TRACES
1.5 OZ COPPER
LAYER 13: INTERMEDIATE TRACES
1.5 OZ COPPER
LAYER 14: INTERMEDIATE TRACES
1.5 OZ COPPER
LAYER 15: INTERMEDIATE TRACES
1.5 OZ COPPER
LAYER 16: INTERMEDIATE TRACES
1.5 OZ COPPER
LAYER 17: INTERMEDIATE TRACES
1.5 OZ COPPER
LAYER 18: INTERMEDIATE TRACES
1.5 OZ COPPER
LAYER 19: INTERMEDIATE TRACES
1.5 OZ COPPER
LAYER 20: INTERMEDIATE TRACES
1.5 OZ COPPER
LAYER 21: INTERMEDIATE TRACES
1.5 OZ COPPER
LAYER 22: INTERMEDIATE TRACES
1.5 OZ COPPER